



GROUNDING APPARATUS OF PRINT CIRCUIT BOARD IN A LIQUID CRYSTAL DISPLAY

BACKGROUND OF THE INVENTION

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(1) Field of the Invention

[0001] This invention relates to an apparatus utilized for grounding a print circuit board of a liquid crystal display, and more particularly to an apparatus for forming an electric connection between the print circuit board and the metal box of the liquid crystal display.

(2) Description of Related Art

[0002] Along with enormous promotions of thin film transistor (TFT) fabrication technique, liquid crystal displays (LCD) are broadly adopted to personal digital assistants (PDA), notebooks (NB), digital cameras (DC), digital videos (DV), mobile phones, etc. Typically, a cold cathode fluorescent lamp (CCFL) is inserted into the LCD as a backlight source. A liquid crystal (LC) driving circuit is used to decode input signals for forming displaying data and scanning sequence data to further control the image of the LCD.

[0003] Ordinarily, in order to increase a display size of the LCD and to simplify the LCD fabrication sequence, the LC driving circuit is usually formed on a print circuit board (PCB) instead of formed traditionally on a glass substrate, accompanied by devices such as tape automated bounding (TAB), chip on glass (COG), chip on film (COF), etc. The PCB having the LC driving circuit is thus able to issue controlling signals to the LCD panel through a flexible flat cable (FFC).

[0004] Because environmental noises may disturb the LC driving circuit by messing the formation of the controlling signals, a proper electric shielding is usually introduced to the PCB so as to remove the charges left on the PCB during LC driving circuit operation. Definitely, upon such an arrangement, a specific grounding apparatus should be added on the PCB.

[0005] In FIG. 1, a typical LCD 10 comprises a metal cover 100, a plastic frame

200, an LCD panel 300, and a PCB 400. The LCD panel 300 and the PCB 400 are fixed on the opposite surfaces of the plastic frame 200 with an inter-connected FFC 410. The metal cover 100 boxes the plastic frame 200 therein to form an interior space for accommodating the LCD panel 300.

5 [0006] In order to prevent a particular electric current in the LC driving circuit from being disturbed by segregated charges on the PCB 400, as shown in FIG. 2, the PCB 400 has two grounding pins 430 formed on both edges 400b adjacent to sidewalls of the metal cover 100b for removing the segregated charges. Also referring to FIG. 1, each grounding pin 430 is fastened to the plastic frame 200 by
10 using a PCB screw 435 and also electrically connected to the metal cover 100 by using an elastic conductive plate 440, which is fastened to the sidewall of the metal cover 100b by sending a grounding screw (not shown in this figure) into a hole 460 on the metal cover 100.

[0007] As mentioned, the grounding pin 430, the elastic conductive plate 440, the PCB screw 435, and the grounding screw are all used to achieve the purpose for grounding the PCB 400 in the art. Yet, with all these parts for grounding the PCB 400, a significant increase of time and labor on assembling an LCD is inevitable. In addition, while in screwing the PCB 400, the power to drive each screw should be carefully controlled so that screws as the fasten device won't
20 damage the PCB 400 or the metal cover 100. Ordinarily, in order to control the screw driving power within a safety range, a power testing apparatus is also used in the assembling process to assure the process reliability.

[0008] Therefore, an improvement of a grounding apparatus targeting to minimize the number of elements and the assembling time without sacrificing the
25 grounding effect is definitely welcome to the skilled persons in the art.

SUMMARY OF THE INVENTION

30 [0009] Accordingly, it is a primary object of the present invention to simplify a grounding apparatus used for grounding a PCB of an LCD, which can also save the time needed to assemble the grounding apparatus.

[0010] An LCD of the present invention comprises an LCD panel, a plastic frame, a metal cover, a PCB, and a conductive film. The plastic frame is used to settle the LCD panel. The metal cover boxes the plastic frame and the LCD panel therein. The PCB is fixed on a lower surface of the plastic frame and connects to the LCD panel by using an FFC extending along a sidewall of the plastic frame. The conductive film taped on a grounding pin of the PCB and a sidewall of the metal cover is used to discharge the segregated charges on the PCB, through the metal cover, to the environment.

[0011] Reference will now be made in detail to the preferred embodiments of the present invention, examples of which are illustrated in the accompanying drawings. Wherever possible, the same reference numbers will be used throughout the drawings to refer to the same or like parts.

BRIEF DESCRIPTION OF THE DRAWINGS

[0012] The present invention will now be specified with reference to its preferred embodiment illustrated in the drawings, in which

[0013] FIG. 1 depicts a schematic view of a PCB in a traditional LCD, in which the PCB is grounded by using a metal cover as a grounding inter-media;

[0014] FIG. 2 depicts a bottom view of the LCD of FIG. 1;

[0015] FIG. 3A depicts a schematic view of a first embodiment of the LCD in accordance with the present invention;

[0016] FIG. 3B depicts a bottom view of the LCD of FIG. 3A;

[0017] FIG. 4A depicts a bottom view of a second embodiment of the LCD in accordance with the present invention;

[0018] FIG. 4B shows the LCD of FIG. 4A further having a passivation film taped thereon;

[0019] FIG. 4C depicts a schematic enlarged view of a lower surface of the PCB of FIG. 4A having a passivation film taped thereon by using a conductive tape with both surfaces gluey;

[0020] FIG. 4D depicts a schematic view of another embodiment of the LCD in accordance with the present invention, in which the a conductive tape with both

surfaces gluey is taped to a lower surface of the PCB; and

[0021] FIG. 5 depicts a schematic view of a third embodiment of the LCD in accordance with the present invention.

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DETAIL DESCRIPTION OF THE PREFERRED EMBODIMENTS

[0022] The invention disclosed herein is directed to a grounding apparatus of a PCB in an LCD. In the following description, numerous details are set forth in

10 order to provide a thorough understanding of the present invention. It will be appreciated by one skilled in the art that variations of these specific details are possible while still achieving the results of the present invention. In other instance, well-known components are not described in detail in order not to unnecessarily obscure the present invention.

15 [0023] In a first embodiment according to the present invention as shown in FIG. 3A, an LCD 10 comprises an LCD panel 300, a plastic frame 200, a metal cover 100, and a PCB 500. The LCD panel 300 is placed on the plastic frame 200. The metal cover 100 for boxing the plastic frame 200 forms an interior space 100b to accommodate both the LCD panel 300 and the plastic frame 200. The PCB 500 is 20 fixed on a lower surface of the plastic frame 200 and connects to the LCD panel 300 by using a flexible flat cable 510 of a proper connecting device (not shown in this figure) to input displaying controlling signals, in which the connecting device can be a tape automated bounding (TAB), a chip on glass (COG), a chip on film (COF), or the like.

25 [0024] Also referring to FIG. 3B, a bottom view of the LCD 10 of FIG. 3A is shown, in which a grounding pin 530 is extended from a blank edge of the PCB 500b (i.e., the side without connecting flexible flat cables 510). A conductive film 520 is taped to the grounding pin 530 and a portion of the nearby metal frame 100b, such that an electrical transmission path can be established to transport 30 segregated charges on the PCB 500 to the environment. Furthermore, the conductive film 520 can also be attached on the plastic frame 200 to fix the PCB 500.

[0025] Particularly, a conductive glue, such as a silver glue, can be coated onto the conductive film 520 so as to have the conductive film 520 firmly hold the grounding pin 530, the adjacent plastic frame 200, and the sidewall of the metal cover 100b. However, in a further simplification of assembly steps that can waive 5 the above-described glue-coating step, a conductive tape (not shown) can be directly used to paste itself on the grounding pin 530, the plastic frame 200, and the sidewall of the metal cover 100b.

[0026] In the foregoing embodiment of FIG. 3B, only one grounding pin 530 is used. However, to achieve a better charge-removing efficiency, a second 10 embodiment having two grounding pins 530 formed on the PCB 500 is shown in FIG. 4A. The two grounding pins 530 are extended from opposite blank edges of the PCB 500b without connecting flexible flat cables 510, and each of the conductive films 520 are taped respectively on the grounding pin 530, the adjacent plastic frame 200, and the nearby sidewall of the metal cover 100b.

15 [0027] In addition, to shield the circuit devices on the PCB 500 from being disturbed by environmental electrical noises, a passivation film 540 as shown in FIG. 4B is formed on an exposed lower surface of the PCB 500. It should be noted that the passivation film 540 also covers both the conductive film 520 and the flexible flat cable 510 so as to achieve a perfect electric shielding effect.

20 [0028] In order to attach the passivation film 540 on the PCB 500, as shown in FIG. 4B, a simple way is to coat glue onto a lower surface of the conductive film 520 and the edges of the PCB 500b before the passivation film 540 is pasted thereon. It is also noted that the glue used is not restricted to the conductive glue.

[0029] As a further simplification, as shown in FIG. 4C, a conductive tape 560 25 with both surfaces gluey is used instead of the conductive film 520 of FIG. 4A. One surface of the conductive tape 560 is taped on the grounding pin 530, the plastic frame 200, and the sidewalls of the metal cover 100b, while the other surface is used to glue a passivation film 540 on a lower surface of the PCB 500 as an electric shielding.

30 [0030] Furthermore, to ensure the passivation film 540 to be perfectly attached on the PCB 500 so as to achieve perfectly electric shielding event, as shown in FIG. 4D, the conductive tape 560 is taped around all four edges of the PCB 500 to

form a larger attaching area and a better adhering effect upon the passivation film 540.

[0031] In the third embodiment of FIG. 5, a grounding pin 580 is fabricated right on the surface of the PCB 500 instead of extended from an edge of the PCB 500b

5 of FIG. 4A. By attaching the grounding pin 580 with the conductive film 590, an electrical transmission path can be formed on the conductive film 590 between the grounding pin 580 and the metal cover 100. Obviously, the design of grounding pin 580 of FIG. 5 is simpler than that of FIG. 4A without degrading the grounding efficiency.

10 [0032] By contrast to the grounding apparatus of FIG. 2, which shows that the PCB 400 is grounded by having the elastic conductive plate 440 fastened on the metal cover 100 with a screw. The grounding apparatus in the present invention has the following advantages:

15 [0033] 1. The devices for grounding PCB 400 in the prior art, such as PCB screw 435, the elastic conductive plate 440, etc., are not required anymore in the grounding apparatus in accordance with the present invention. Therefore, the cost to assemble the LCD and the assembling time can be reduced.

20 [0034] 2. As shown in FIG. 4A, a conductive film 520 is used instead of the grounding apparatus of FIG. 2, and the conductive film 520 is fixed by taping to form the electric transmission path for grounding the PCB 500. Therefore, the problem resulted from controlling the screw driving power of the grounding apparatus of FIG. 2 needs not to be concerned.

25 [0035] 3. As shown in FIG. 4C, by using a conductive tape 560 with both surfaces gluey to form an electric transmission path for grounding the PCB 500, the passivation film 540 can be fixed on the PCB 500 in the same process. Therefore, the process to assemble the grounding apparatus is simplified.

30 [0036] 4. In the third embodiment, the grounding pin 580 of FIG. 5 is fabricated right on the surface of the PCB 500 instead of the grounding pin 430 of FIG. 2 extended from an edge of the PCB 400b to reach the conductive

elastic plate 440. It is clear that the fabrication process of the grounding pin 580 is simpler than that of the grounding pin 530.

[0037] With the example and explanations above, the features and spirits of the invention will be hopefully well described. Those skilled in the art will readily observe that numerous modifications and alterations of the device may be made when retaining the teaching of the invention. Accordingly, the above disclosure should be construed as limited only by the metes and bounds of the appended claims.